

AMENDMENTS TO THE SPECIFICATION

On the cover page and page 1, please replace the title with the following:

~~OPTIMIZED-LOW LEAKAGE DIODES, INCLUDING PHOTODIODES~~

On page 13, please replace the paragraph beginning on line 9 with the following:

For the photodiode 215 of the ~~second~~third embodiment, the processing is essentially complete at this stage, and conventional processing methods may then be used to form contacts and wiring to connect the photodiode 215 to an imager apparatus. For example, the entire surface of the photodiode may then be covered with a passivation layer of, e.g., silicon dioxide or BPSG, which is CMP planarized and etched to provide contact holes, which are then metallized to provide contacts to the photodiode 215.

On page 14, please replace the paragraph beginning on line 9 with the following:

For the photodiode 215 of the ~~second~~third embodiment, the processing is essentially complete at this stage, and conventional processing methods may then be used to form contacts and wiring to connect the photodiode 215 to an imager apparatus as described in more detail above.